

### ABSTRACT

The present invention provides a rigid circuit member obtained by bending a composite laminate comprising a circuit conductor made of a metal foil interposed between plastic films having an elastic modulus of not less than  $450 \text{ kg/mm}^2$  with an adhesive, characterized in that as said plastic film there is used a polyethylene naphthalate film. The present invention also provides a circuit board adapted to be connected to a conductor on a rigid substrate, characterized in that said circuit conductor is interposed between polyethylene naphthalate films. The present invention further provides a printed circuit board, comprising a polyethylene naphthalate film having an elastic modulus of not less than  $500 \text{ kg/mm}^2$ , not more than  $1.5 \times 10^{-5}/^\circ\text{C}$ , a hygroscopic expansion coefficient of not more than  $1.2 \times 10^{-5}/\% \text{RH}$ , a water vapor permeability of not more than  $15 \text{ g/m}^2/\text{mil-day}$ , a percent water absorption of not more than 2% and a melting point of not higher than  $280^\circ\text{C}$  and a conductor circuit integrated into a laminate with an adhesive layer provided interposed therebetween.